mail

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



This drawing and the information set forth here-on are the property of tyco electronics and are to be held in trust and confidence. Publication, duplication, disclosure, or use for any purpose not expressly authorized in writing by tyco electronics is prohibited.	REVISIONS				
	LTR		DESCRIPTION	DATE	APPROVED
	A	PER ECO-10-003119		FEB/11/2010	M.HIGGY
NOTES	В	PER ECO-11-006734		Mar/31/2011	M.HIGGY

1. PACKAGE: 500 FEET PER REEL.

2. LENGTH TOLERANCE: ±2%

- 3. WHEN INSTALLED IN DIRECT CONTACT WITH FLAT CONDUCTOR CABLE, SURFACE TRANSFER IMPEDANCE LEVEL IS APPLICATION DEPENDENT.
- 4. THIS PRODUCT IS DESIGNED TO MEET THE REQUIREMENTS OF TYCO ELECTRONICS/RAYCHEM SPECIFICATION C-6119, QUALIFICATION IS PENDING.
- 5. SEE PAGE #2 FOR SPECIFIC CUSTOMER'S FOLDING REQUIREMENTS PRIOR TO EACH SHIPMENT.



Fold Endurance

5.1 Test Procedure and Acceptance :

7 samples at 6 inch length each of the shield material shall be used for performing this folding test. The sample shall be folded at a right angle as shown in Figure 1 and placed on horizontal surface between two smooth surfaced flat metal plates.

A load (weight/force) of 30 ± 1 lbf/in2 shall be placed over the triangular area of the fold for a 15 minute duration. The specimen shall then be unfolded and the equivalent load applied to the unfolded, creased portion of the specimen for 15 minutes. This cycle of folding and unfolding shall be repeated once more, with the fold at the same place and in the same direction.

5.2 Inspection Criteria at the Folded Area

The specimen shall then be inspected at the folding area using the naked eye for evidence of cracks or delamination of the Polyimide layer and copper layer. There shall be no evidence of cracks or delamination of the Polyimide layer and copper layer. Delamination will be cause for rejection.

Stretching of the Polyimide layer, at the fold line characterized by an opaque line is acceptable as long as the width of the opaque line does not exceed 0.020 inches in width, see figure 2.

5.3 Inspection Criteria Outside the Folded Area:

The specimen shall be inspected for interior voids and delamination outside the folding area. The total areas of any evidence of Interior voids, or delamination between the Polyimide layers and copper layer should not exceed 0.001 inch square in an area of one inch square of the shield material. Otherwise the material will be rejected.

